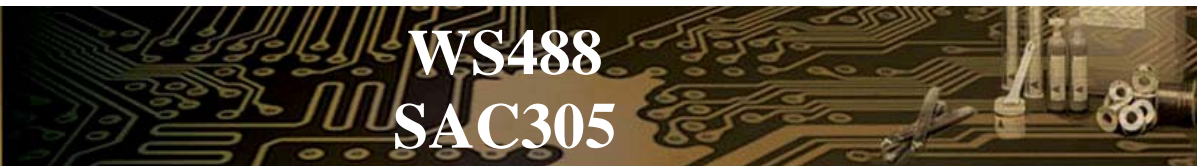




WS488 SAC305



Water Soluble Solder Paste

Features:

- Excellent Wetting
- Superior Slump Resistance
- Aqueous Wash with Water
- Extended Cleaning Window
- 8 Hour + Stencil Life
- Large Process Window

Description:

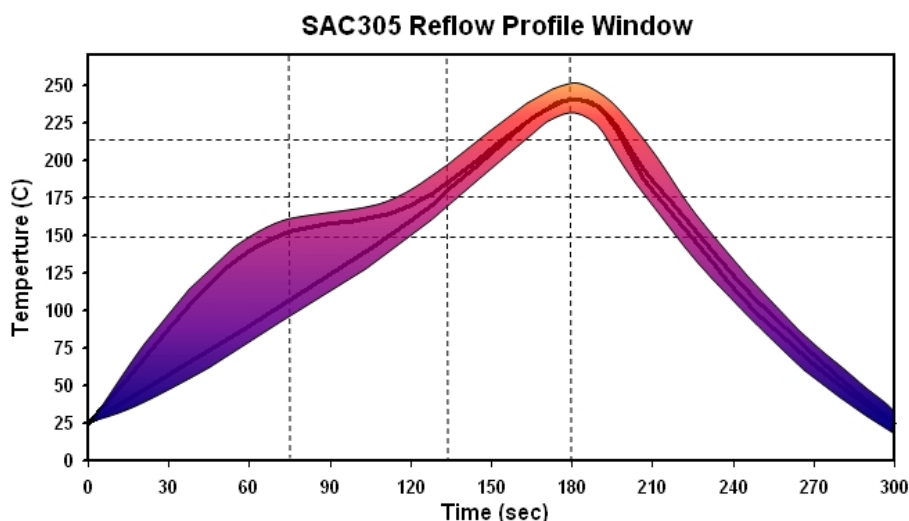
AIM's WS488 water soluble solder paste has been designed to wet virtually any solderable electronic surfaces, components, assemblies, and substrates. WS488 offers superior slump resistance, as well as excellent print characteristics and 8+ hours of stencil life. WS488 is compatible with all leaded and lead-free alloys, and has been developed for use in a wide range of applications. Easily cleaned in tap water, this all purpose water soluble product was created to meet the industry's demand for a consistently reliable water soluble product.

Printing:

- Apply sufficient paste to the stencil to allow a smooth, even roll during the print cycle (a bead diameter of 12 to 16 mm ($\frac{1}{2}$ to $\frac{5}{8}$ inch) is normally sufficient to begin).
- Apply small amounts of fresh solder paste to the stencil at controlled intervals to maintain paste chemistry and workable properties.
- WS488 provides the necessary tack time and force for today's high speed placement equipment, which will enhance product performance and reliability.
- Snap-off distance = On Contact 0.00 mm (0.00")
- PCB Separation Distance = 0.75-2.0 mm (.030-.080")
- PCB Separation Speed = Slow-Medium
- Squeegee Pressure = 0.30-0.75 kg/cm (.6 - 1.7 lbs/In.) of blade
- Squeegee Stroke Speed = 25-50 mm/sec (1 - 2 In./sec)
- Note: Recommended initial printer settings above are dependent on PCB and pad design
- Cleaning of your stencil will vary by application; however, it can be accomplished using AIM 200AX-10 stencil cleaner

Reflow Profile:

Either a straight ramp-spike or ramp-soak-spike profile can be used as shown below. Both profiles would have a similar peak temperature and time above liquidus (TAL). The shaded area defines the process window. Oven efficiency, board size/mass, component type and density all influence the final profile for a given assembly. These profiles are starting points, and processing boards with thermal-couples attached is recommended to optimize the process.



<i>RATE OF RISE</i> 2 °C / SEC MAX	<i>RAMP TO</i> 150 °C (300°F)	<i>PROGRESS THROUGH</i> 150°C-175°C (300°F-345°F)	<i>TO PEAK TEMP</i> 230 °C-245°C (445°F-475°F)	<i>TIME ABOVE</i> 217 °C (425°F)	<i>COOLDOWN</i> ≤ 4°C / SEC	<i>PROFILE LENGTH</i> AMBIENT TO PEAK
Standard Profile	≤ 75 Sec	30-60 Sec	45-75 Sec	30-60 Sec	45± 15 Sec	2.75-3.5 Min

- ❖ THE RECOMMENDED REFLOW PROFILE FOR WS488 IS PROVIDED AS A GUIDELINE. OPTIMAL PROFILE MAY DIFFER DUE TO OVEN TYPE, ASSEMBLY LAYOUT, OR OTHER PROCESS VARIABLES. CONTACT AIM TECHNICAL SUPPORT IF YOU REQUIRE ADDITIONAL PROFILING ASSISTANCE.
- ❖ THE REFLOW PROFILE FOR THE SAC305 PASTES USING A VAPOR PHASE REFLOW OVEN: PEAK TEMPERATURE RANGE IS 230°C – 245°C.

WS488 Compatible Products:

- Electropure Solder Bar
- WS488 Tacky Flux
- WS715; WS375 Spray Flux
- WS482 Cored Wire
- Epoxy 4089 – Chip Bonding Epoxy
- 200AX – Stencil Cleaner

Cleaning:

WS488 can be cleaned easily with normal tap water. Deionized water is recommended for the final rinse. A temperature of 38°C (100°F) - 66°C (150°F) is sufficient for removing residues. An in-line or other pressurized spray cleaning system is suggested, but is not required.

Handling and Storage:

- WS488 has a refrigerated shelf life of 6 months at 4°C (40°F) - 12°C (55°F).
- Allow the solder paste to warm naturally to ambient temperature (8 hrs.) prior to breaking the seal for use.
- Mix the product lightly and thoroughly for 1 to 2 minutes to ensure even distribution of any separated material.
- Do not store new and used paste in the same container, and reseal any opened containers while not in use.
- Replace the internal plug and cap of the 500 gram jars to ensure the best possible seal.

Safety:

- Use with adequate ventilation and proper personal protective equipment
- Refer to the accompanying Material Safety Data Sheet Do not dispose of any lead-containing materials in non-approved containers.

Physical Properties:

<i>ITEM</i>	<i>SPECIFICATION</i>
Appearance	Gray, Smooth, Creamy
Alloy	SAC305
Melting Point	217°-218°C
Particle Size	T3, T4, T5
General Metal Loading	88.5% (T3)
Viscosity	Print/Dispense Versions Available
Packaging	Available in all industry standard packaging.

Test Data Summary:

CLASSIFICATION			
Product Name	IPC Classification	Copper Mirror TM 650 2.2.32	Silver Chromate TM 650 2.2.33
WS488	ORM0	< 50% Breakthrough – M	Pass
POWDER TESTING			
No.	Item	Results	Test Method
1	Powder Size	Type 3 – 45-25 micron Type 4 – 38-20 micron	IPC TM 650 2.2.14
2	Powder Shape	Spherical	Microscope
FLUX MEDIUM TESTING			
No.	Item	Results	Test Method
1	Acid Value	55.17 mg KOH/g Flux	IPC TM 650 2.3.13
2	Fluorides Spot Test	No Fluoride	IPC TM 650 2.3.35.1 IPC TM 650 2.3.35.2
3	Corrosivity Test/ Copper Mirror	< 50% Breakthrough – M	IPC TM 650 2.3.32
4	Halide-Free/Silver Chromate Paper Test	Pass	IPC TM 650 2.3.33
5	Non-Volatile Residue	3.0%	IPC TM 650 2.3.34
6	Surface Insulation Resistance (Solder paste was reflowed on test coupons, left at ambient temperatures for 2 weeks, then cleaned with 55-58°C tap water for 120 sec, and allowed to air dried for 30 min before testing)	Control Coupons > 1E9Ω at 96 & 168 h. - Pass Sample Coupons > 1E8Ω at 96 & 168 h. - Pass > No dendrite growth or corrosion, after a visual inspection - pass	IPC TM 650 2.6.3.3
7	Compatibility Test	See list of recommended products above	GR-78-CORE
VISCOSITY TESTING			
No.	Item	Results	Test Method
1	T-Bar Spindle Test Method	900 ± 10% kcps	IPC TM 650 2.4.34
SOLDER PASTE TESTING			
No.	Item	Results	Test Method
1	Tack Test	30.5 gf	IPC TM 650 2.4.44
2	Tack Test	82.8 gf	JIS Z 3284 Annez 9
3	Solder Ball Test	Pass	IPC TM 650 2.4.43
4	Wetting Test	Pass	IPC TM 650 2.4.45
5	Paste Shelf Life	4°C (39°F) = 6 months	AIM TM 125-11
6	Solder Paste Slump Test	Pass	IPC TM 650 2.4.35

Manufacturing and Distribution Worldwide
Americas +1-401-463-5605 · Europe +44-1737-222-258 · Asia-Pacific +852-2649-7183 · info@aimsolder.com · www.aimsolder.com
AIM IS ISO9001:2000 CERTIFIED

The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. All information pertaining to solder paste is produced with 45-micron powder. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to <http://www.aimsolder.com/terms.cfm> to review AIM's terms and conditions.

04/09
Rev 2